

KYOCERA KE-200DH

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

We have several grades of compounds w/good balance between cost and performance to meet wide requirements of customers.

Strong Points

Good Adhesion Strength even Under High Temperature Reflow Soldering Process.

Achieve Good Reflow Resistance (JEDEC Level 2) with Good Moldability.

JEDEC Level 1 in Case Smaller Package is possible.

Line Up for Several Lead Frame Types. (Cu,42Alloy,Pd/Au plated)

Application

SOP, Larger QFP, Smaller QFP, DIP, TO-PKG, DPAK, SOT

General Information		
Features	Good Adhesion	
	Good Moldability	
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	2.00	g/cm ³
Spiral Flow	85.0	cm
Mechanical	Nominal Value	Unit
Flexural Modulus	18000	MPa
Flexural Strength	145	MPa
Thermal	Nominal Value	Unit
Glass Transition Temperature	130	°C
CLTE - Flow		
-- 1	1.1E-5	cm/cm/°C
-- 2	4.5E-5	cm/cm/°C
Uncured Properties	Nominal Value	Unit
Gel Time	0.38	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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